TL497A 500-mA PEAK STEP-UP, STEP-DOWN, INVERTING SWITCHING VOLTAGE REGULATOR

SLVS009F - JUNE 1976 - REVISED FEBRUARY 2005

- High Efficiency . . . 60% or Greater
- Peak Switch Current . . . 500 mA
- Input Current Limit Protection
- TTL-Compatible Inhibit
- Adjustable Output Voltage
- Input Regulation . . . 0.2% Typ
- Output Regulation . . . 0.4% Typ
- Soft Start-Up Capability
- Can be Used in Buck, Boost, and Inverting Configurations

COMP INPUT [1 14] V_{CC} INHIBIT [2 13] CUR LIM SENS FREQ CONTROL [3 12] BASE DRIVE† SUBSTRATE [4 11] BASE† GND [5 10] COL OUT CATHODE [6 9] NC ANODE [7 8] EMIT OUT

D, N, OR PW PACKAGE

NC - No internal connection

description/ordering information

The TL497A incorporates all the active functions required in the construction of switching voltage regulators. It also can be used as the control element to drive external components for high-power-output applications. The TL497A was designed for ease of use in step-up, step-down, or voltage-inversion applications requiring high efficiency.

The TL497A is a fixed-on-time variable-frequency switching-voltage-regulator control circuit. The switch-on time is programmed by a single external capacitor connected between FREQ CONTROL and GND. This capacitor, C_T , is charged by an internal constant-current generator to a predetermined threshold. The charging current and the threshold vary proportionally with V_{CC} . Thus, the switch-on time remains constant over the specified range of input voltage (4.5 V to 12 V). Typical on times for various values of C_T are as follows:

TIMING CAPACITOR, C _T (pF)	200	250	350	400	500	750	1000	1500	2000
ON TIME (μs)	19	22	26	32	44	56	80	120	180

The output voltage is controlled by an external resistor ladder network (R1 and R2 in Figures 1, 2, and 3) that provides a feedback voltage to the comparator input. This feedback voltage is compared to the reference voltage of 1.2 V (relative to SUBSTRATE) by the high-gain comparator. When the output voltage decays below the value required to maintain 1.2 V at the comparator input, the comparator enables the oscillator circuit, which charges and discharges C_T as described above. The internal pass transistor is driven on during the charging of C_T . The internal transistor can be used directly for switching currents up to 500 mA. Its collector and emitter are uncommitted, and it is current driven to allow operation from the positive supply voltage or ground. An internal Schottky diode matched to the current characteristics of the internal transistor also is available for blocking or commutating purposes. The TL497A also has on-chip current-limit circuitry that senses the peak currents in the switching regulator and protects the inductor against saturation and the pass transistor against overstress. The current limit is adjustable and is programmed by a single sense resistor, R_{CL} , connected between V_{CC} and CUR LIM SENS. The current-limit circuitry is activated when 0.7 V is developed across R_{CL} . External gating is provided by the INHIBIT input. When the INHIBIT input is high, the output is turned off.

Simplicity of design is a primary feature of the TL497A. With only six external components (three resistors, two capacitors, and one inductor), the TL497A operates in numerous voltage-conversion applications (step-up, step-down, invert) with as much as 85% of the source power delivered to the load. The TL497A replaces the TL497 in all applications.

The TL497AC is characterized for operation from 0° C to 70° C. The TL497AI is characterized for operation from -40° C to 85° C.



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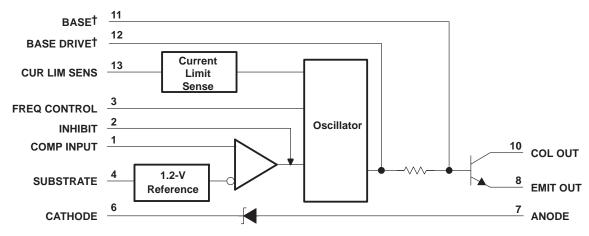
[†] BASE (11) and BASE DRIVE (12) are used for device testing only. They normally are not used in circuit applications of the

AVAILABLE OPTIONS

	PA	CHIP		
TA	SMALL-OUTLINE (D)	PLASTIC DIP (N)	(N) SMALL-OUTLINE (PW)	
0°C to 70°C	TL497ACD	TL497ACN	TL497ACPW	TL497AY
-40°C to 85°C	TL497AID	TL497AIN	_	_

The D and PW packages are only taped and reeled. Add the suffix R to the device type (e.g., TL497ACPWR). Chip forms are tested at 25°C.

functional block diagram



[†]BASE and BASE DRIVE are used for device testing only. They normally are not used in circuit applications of the device.

TL497A 500-mA PEAK STEP-UP, STEP-DOWN, INVERTING SWITCHING VOLTAGE REGULATOR

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)		15 V
Output voltage, VO		
Input voltage, V _I (COMP INPUT)		
Input voltage, V _I (INHIBIT)		
Diode reverse voltage		35 V
Power switch current		750 mA
Diode forward current		750 mA
Package thermal impedance, θ _{JA} (see Notes 2 and 3)	: D package	86°C/W
•	N package	101°C/W
	PW package	113°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 60) seconds	260°C
Storage temperature range, T _{stq}		-65°C to 150°C

[†]Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except diode voltages, are with respect to network ground terminal.

- 2. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can impact reliability.
- 3. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions

			MIN	MAX	UNIT
Supply voltage, V _{CC}			4.5	12	V
High-level input voltage, VIH	INHIBIT pin				V
Low-level input voltage, V _{IL}	INHIBIT pin	INHIBIT pin			
Output voltage	Step-up configuration (see Figure 1)	V _I + 2	30		
	Step-down configuration (see Figure 2)	V _{ref}	V _I – 1	V	
	Inverting regulator (see Figure 3)	-V _{ref}	-25		
Power switch current	·			500	mA
Diode forward current				500	mA
Operating free-air temperature range, T _Δ				70	°C
Operating free-all temperature rang	⊏, ≀Д	TL497AI	-40	85	C

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electrical characteristics over recommended operating conditions, $V_{CC} = 6 \text{ V}$ (unless otherwise noted)

			_ +	1	L497AC	;		TL497AI		
PARAMETER	TEST CO	ONDITIONS	T _A †	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
High-level input current, INHIBIT	V _{I(I)} = 5 V		Full range		0.8	1.5		0.8	1.5	mA
Low-level input current, INHIBIT	V _{I(I)} = 0 V	V _{I(I)} = 0 V			5	10		5	20	μΑ
Comparator reference voltage	V _I = 4.5 V to	V _I = 4.5 V to 6 V		1.08	1.2	1.32	1.14	1.2	1.26	V
Comparator input bias current	V _I = 6 V	V _I = 6 V			40	100		40	100	μΑ
0 11 11 11		I _O = 100 mA	25°C		0.13	0.2		0.13	0.2	.,
Switch on-state voltage	V _I = 4.5 V	$I_0 = 500 \text{ mA}$	Full range			0.85			1	V
			25°C		10	50		10	50	
Switch off-state current	$V_1 = 4.5 V$	VO = 30 V	Full range			200			500	ο μΑ
Sense voltage, CUR LIM SENS	V _I = 6 V		25°C	0.45		1	0.45		1	V
	I _O = 10 mA		Full range		0.75	0.85		0.75	0.95	
Diode forward voltage	$I_{O} = 100 \text{ m/s}$	I _O = 100 mA			0.9	1		0.9	1.1	V
	I _O = 500 mA		Full range		1.33	1.55		1.33	1.75	
D'a da manana and ta ma	ΙΟ = 500 μΑ		Full range				30			
Diode reverse voltage	$I_{O} = 200 \mu A$		Full range	30						V
			25°C		11	14		11	14	
On-state supply current			Full range			15		_	16	mA
0" -1-1			25°C		6	9		6	9	4
Off-state supply current			Full range			10			11	mA

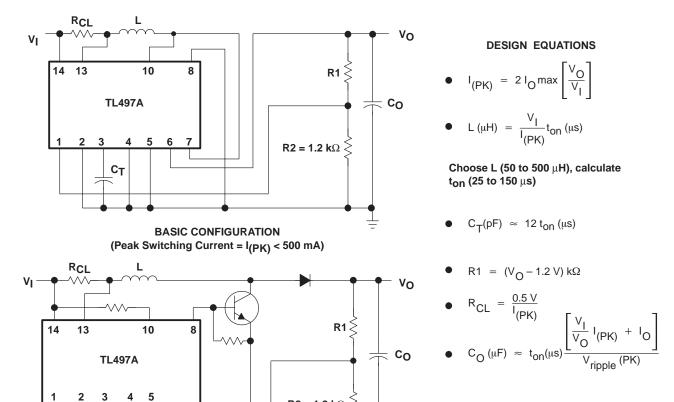
[†] Full range is 0°C to 70°C for the TL497AC and -40°C to 85°C for the TL497AI.

electrical characteristics over recommended operating conditions, V_{CC} = 6 V, T_A = 25°C (unless otherwise noted)

DADAMETED	TEGT CONDITIONS	TL497AY	
PARAMETER	TEST CONDITIONS	MIN TYP MAX	UNIT
High-level input current, INHIBIT	V _{I(I)} = 5 V	0.8	mA
Low-level input current, INHIBIT	V _{I(I)} = 0 V	5	μΑ
Comparator reference voltage	V _I = 4.5 V to 6 V	1.2	V
Comparator input bias current	V _I = 6 V	40	μΑ
Switch on-state voltage	$V_I = 4.5 \text{ V}, \qquad I_O = 100 \text{ mA}$	0.13	V
Switch off-state current	$V_{I} = 4.5 \text{ V}, \qquad V_{O} = 30 \text{ V}$	10	μΑ
	I _O = 10 mA	0.75	
Diode forward voltage	I _O = 100 mA	0.9	V
	I _O = 500 mA	1.33	
On-state supply current		11	mA
Off-state supply current		6	mA



[‡] All typical values are at $T_A = 25$ °C.

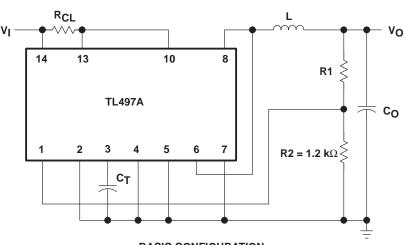


EXTENDED POWER CONFIGURATION (using external transistor)

Ст

Figure 1. Positive Regulator, Step-Up Configurations

R2 = 1.2 kΩ \ge



BASIC CONFIGURATION (Peak Switching Current = I(PK) < 500 mA)

DESIGN EQUATIONS

- \bullet $I_{(PK)} = 2I_{O} \max$
- $\bullet \ \ L \ (\mu H) \ \ = \ \frac{V_I V_O}{I_{(PK)}} t_{ON}(\mu s)$

Choose L (50 to 500 $\mu\text{H})\text{, calculate }t_{\mbox{on}}$ (10 to 150 $\mu\text{s})$

- $C_T(pF) \approx 12 t_{on}(\mu s)$
- R1 = $(V_O 1.2 \text{ V}) \text{ k}\Omega$

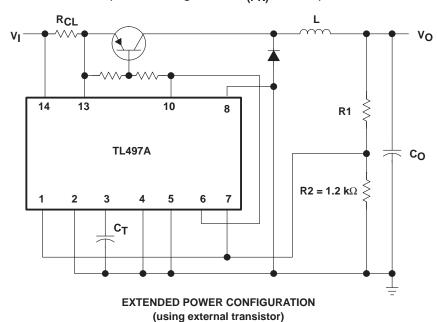
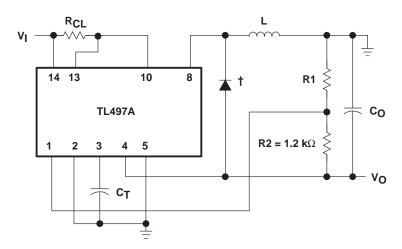
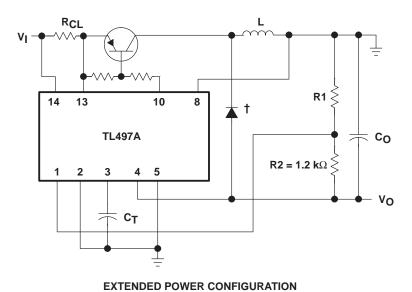


Figure 2. Positive Regulator, Step-Down Configurations



BASIC CONFIGURATION
(Peak Switching Current = I(PK) < 500 mA)



DESIGN EQUATIONS

$$\bullet I_{(PK)} = 2I_{O} \max \left[1 + \frac{|V_{O}|}{V_{I}} \right]$$

•
$$L(\mu H) = \frac{V_I}{I(PK)} t_{ON}(\mu s)$$

Choose L (50 to 500 μ H), calculate t_{on} (10 to 150 μ s)

•
$$C_T(pF) \approx 12 t_{on}(\mu s)$$

• R1 =
$$(|V_{\Omega}| - 1.2 \text{ V}) \text{ k}\Omega$$

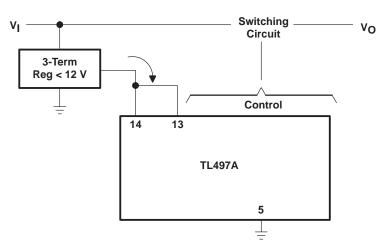
$$R_{CL} = \frac{0.5 \text{ V}}{I_{(PK)}}$$

$$C_{O} (\mu F) \approx t_{ON}(\mu s) \frac{\left[\frac{V_{I}}{|V_{O}|} I_{(PK)} + I_{O}\right]}{V_{ripple} (PK)}$$

(using external transistor)

Figure 3. Inverting Applications

[†]Use external catch diode, e.g., 1N4001, when building an inverting supply with the TL497A.



EXTENDED INPUT CONFIGURATION WITHOUT CURRENT LIMIT

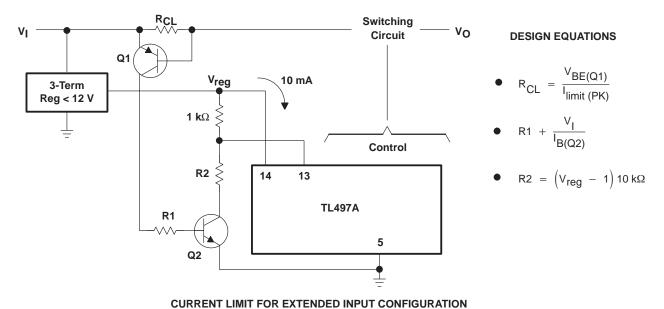


Figure 4. Extended Input Voltage Range (V_I > 12 V)

www.ti.com 2-May-2025

PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ MSL rating/ Ball material Peak reflow		Op temp (°C)	Part marking (6)
partition	(1)	(2)			(3)	(4)	(5)		(0)
TL497ACD	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL497AC
TL497ACDR	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL497AC
TL497ACN	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TL497ACN
TL497ACNSR	Active	Production	SOP (NS) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL497A
TL497ACPWR	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	T497A
TL497AID	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL497AI
TL497AIDR	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL497AI
TL497AIN	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	TL497AIN

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



PACKAGE OPTION ADDENDUM

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



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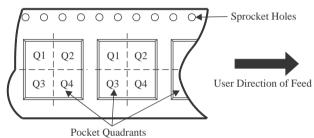
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL497ACDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL497ACNSR	SOP	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
TL497ACPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TL497AIDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1



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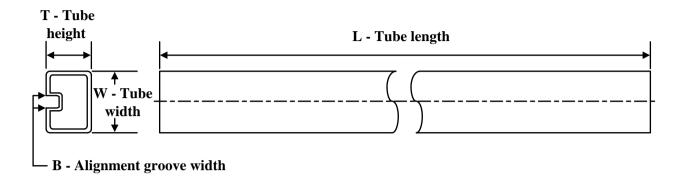
*All dimensions are nominal

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	Device	Package Type Package Drawing		Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
	TL497ACDR	SOIC	D	14	2500	340.5	336.1	32.0
ı	TL497ACNSR	SOP	NS	14	2000	356.0	356.0	35.0
ı	TL497ACPWR	TSSOP	PW	14	2000	356.0	356.0	35.0
	TL497AIDR	SOIC	D	14	2500	340.5	336.1	32.0



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TUBE

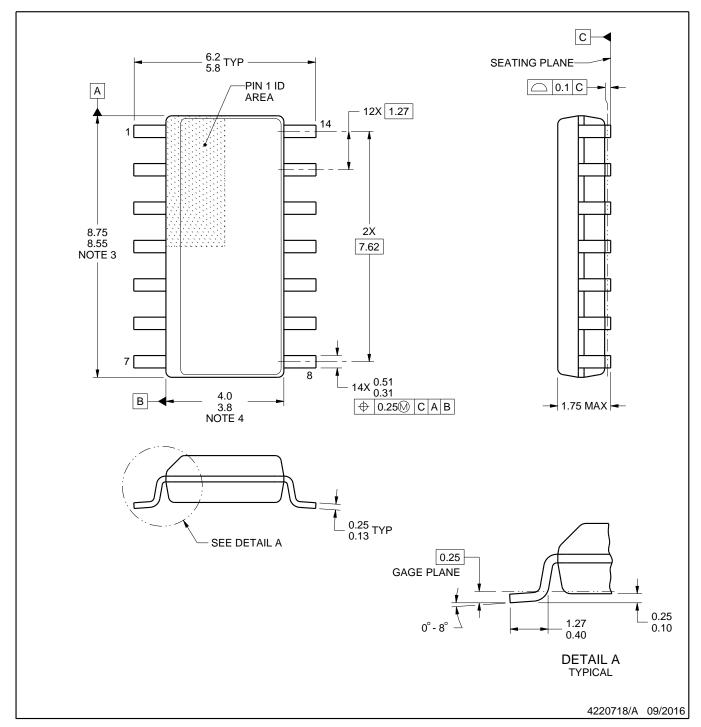


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
TL497ACD	D	SOIC	14	50	507	8	3940	4.32
TL497ACN	N	PDIP	14	25	506	13.97	11230	4.32
TL497ACN	N	PDIP	14	25	506	13.97	11230	4.32
TL497ACNE4	N	PDIP	14	25	506	13.97	11230	4.32
TL497ACNE4	N	PDIP	14	25	506	13.97	11230	4.32
TL497AID	D	SOIC	14	50	507	8	3940	4.32
TL497AIN	N	PDIP	14	25	506	13.97	11230	4.32



SMALL OUTLINE INTEGRATED CIRCUIT



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT

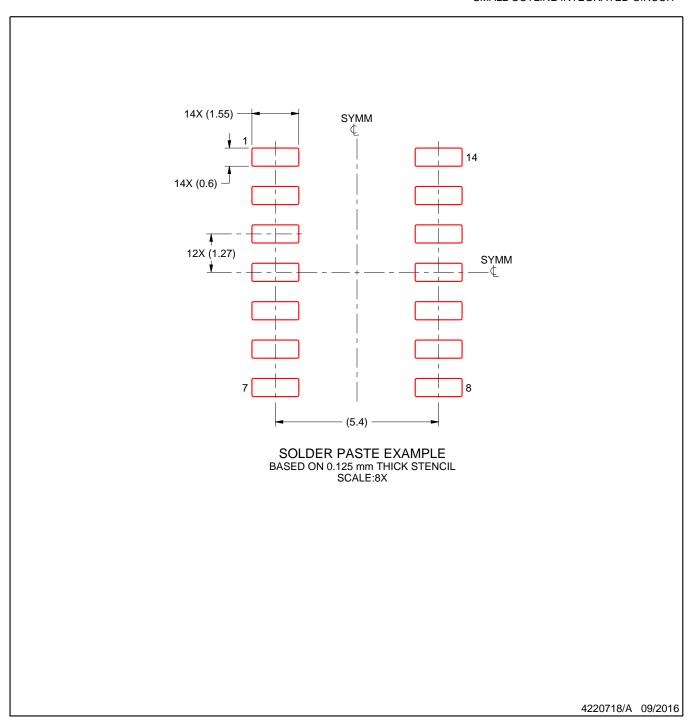


NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- a. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

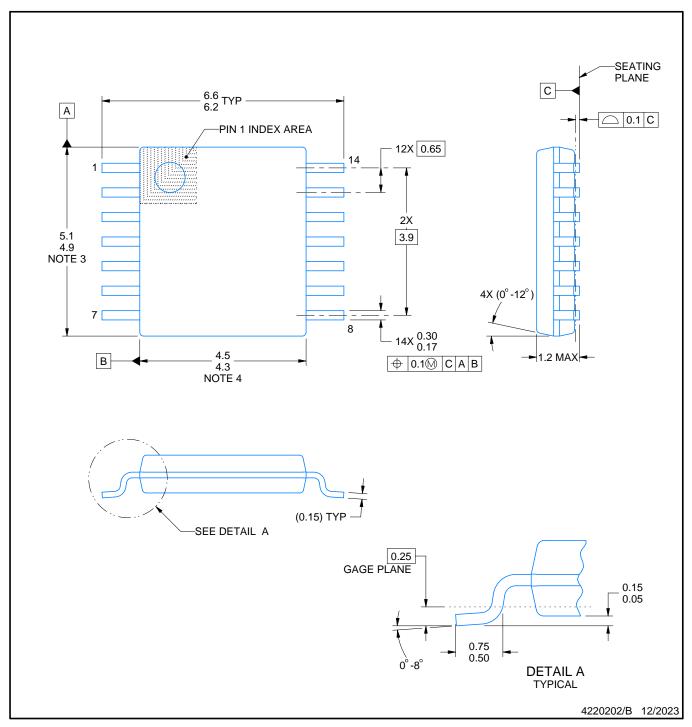


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SMALL OUTLINE PACKAGE



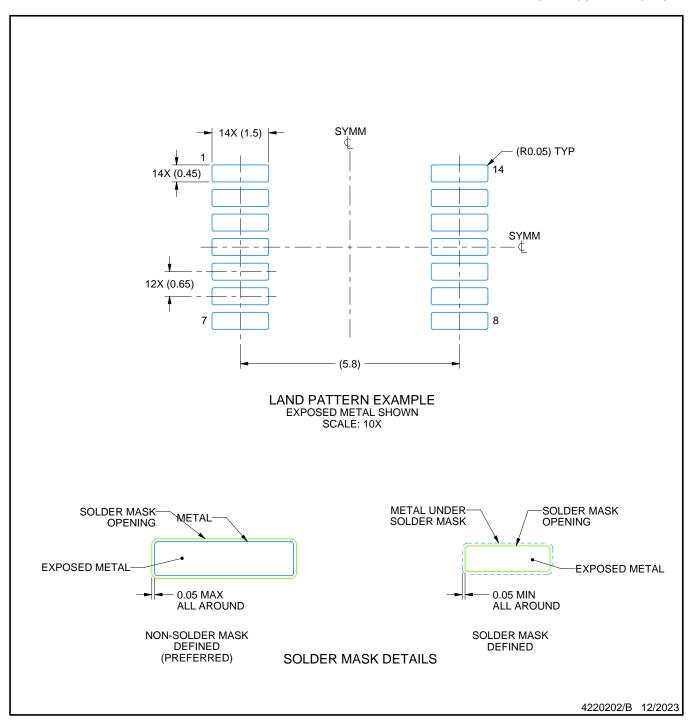
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE

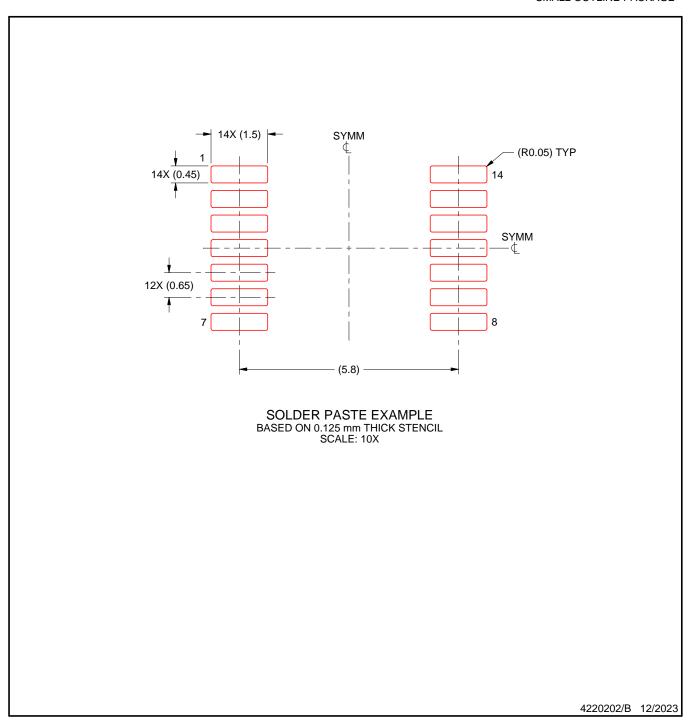


NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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